

AMENDMENTS

1. (currently amended) A target, comprising an inorganic target material and a backing plate bonded with a soldering material between them, wherein at least one of the target material and the backing plate is coated with a coupling agent of a semi-metal oxide or a metal oxide that has a hydrolyzable group.

2. (currently amended) The target of claim 1, wherein the coupling agent comprises an oxide of an IVa group element in the Periodic Table of Elements titanium oxide, zirconium oxide or hafnium oxide.

3. (original) The target of claim 1, wherein the coupling agent comprises a silane coupling agent.

4. (currently amended) A method for manufacturing a target by bonding an inorganic target material and a backing plate with a soldering material between them, comprising:

coating a coupling agent of a semi-metal oxide or a metal oxide on a bonding surface of at least one of the target material and the backing plate, wherein the coupling agent has a hydrolyzable group;

disposing a molten soldering material on the bonding surface of at least one of the target material and the backing plate; and

bonding the target material and the backing plate via the soldering material.

5. (currently amended) The method of claim 4, wherein the coupling agent comprises an oxide of an IVa group element in the Periodic Table of Elements titanium oxide, zirconium oxide or hafnium oxide.

6. (original) The method of claim 4, wherein the coupling agent comprises a silane coupling agent.

7. (new) The target of claim 1, wherein the soldering material is selected from the group consisting of indium (In), indium alloys, tin (Sn) and tin alloys.

8. (new) The method of claim 4, wherein the soldering material is selected from the group consisting of indium (In), indium alloys, tin (Sn) and tin alloys.